

The Micro Vertex Detector of the CBM Experiment

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on behalf of the CBM-MVD Collaboration

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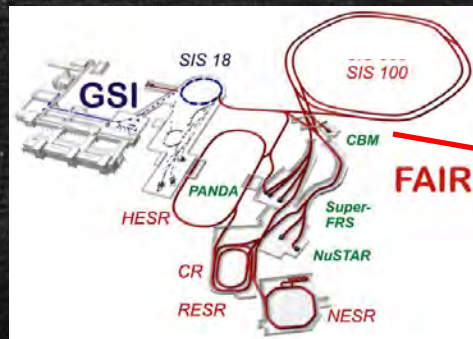
CONF₁₂ - XIth Quark Confinement and the Hadron Spectrum

Outline

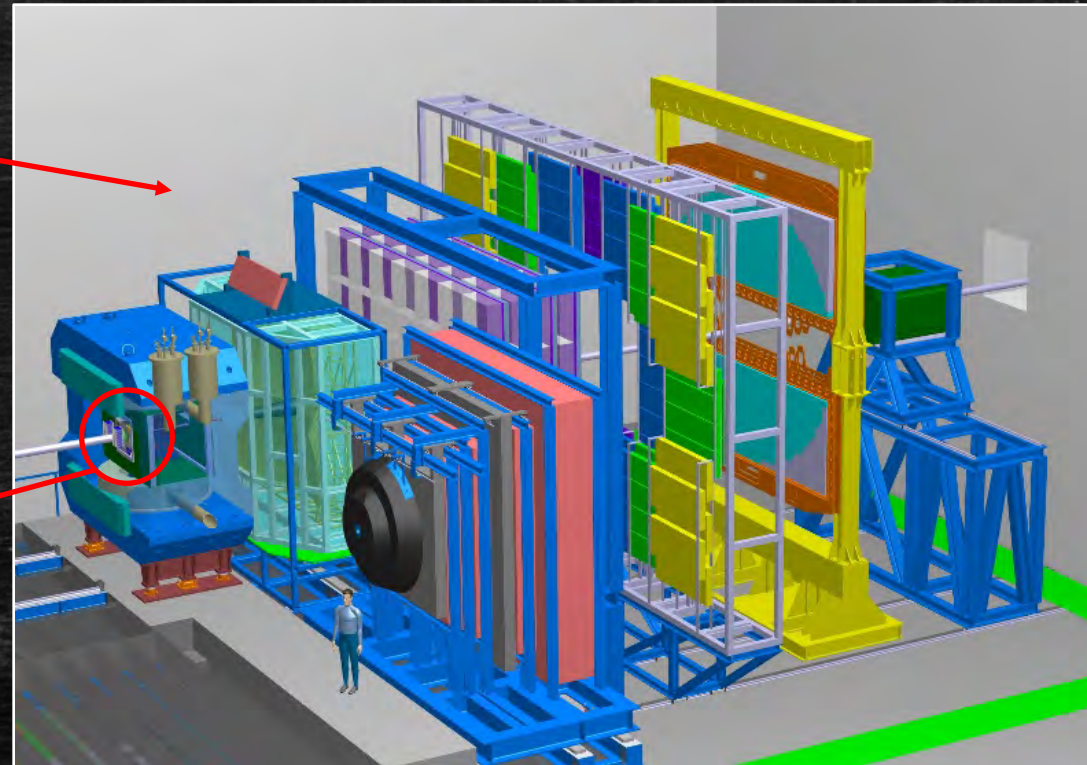
- Introduction
- Design of the MVD
- Status and Results of R&D
- Summary and Outlook

The Compressed Baryonic Matter Experiment and its Micro Vertex Detector

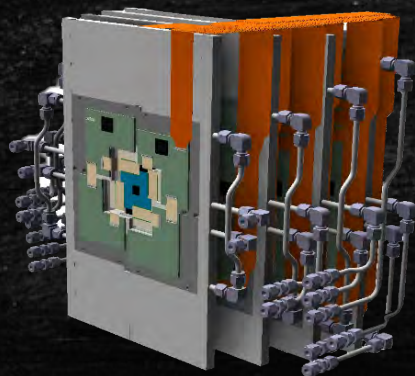
FAIR @ Darmstadt, Germany



The fixed-target CBM experiment

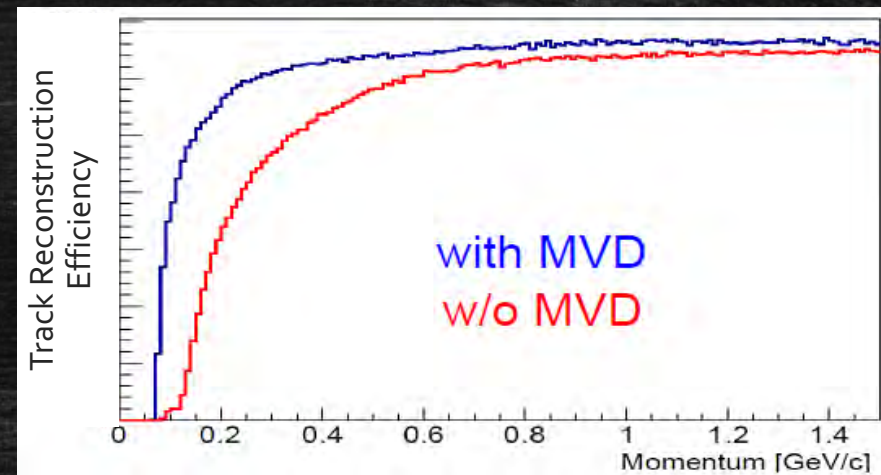


The CBM - MVD



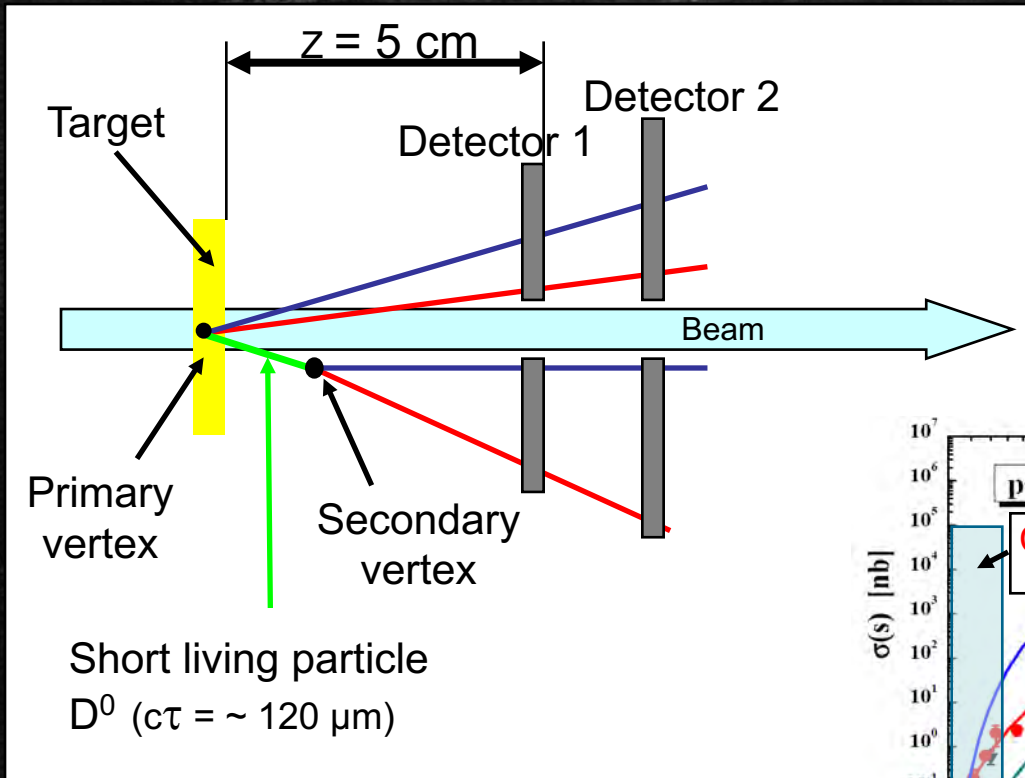
The Mission of the Micro Vertex Detector

- 1) Reconstruction of open-charm particles in p-A collisions
- 2) Light vector mesons:
Conversion pair suppression
- 3) Multi-strange particles and hyperons
- 4) Low momentum tracking



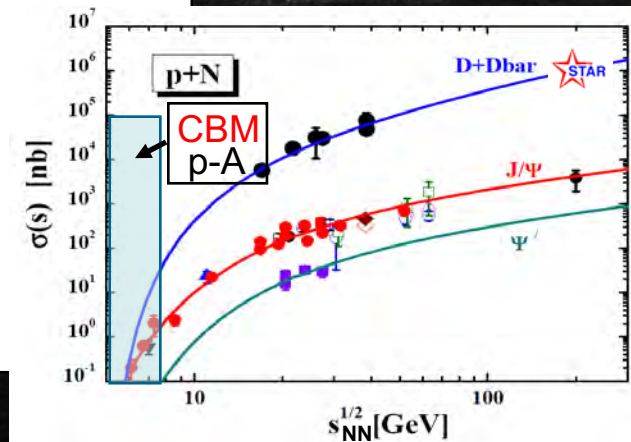
Design Considerations for the MVD

Design driven by open charm reconstruction (historically the primary mission):



Need excellent sec. vertex resolution ($\sim 50 \mu\text{m}$)

- Very good spatial resolution ($\sim 5 \mu\text{m}$)
- Very thin detector stations (avoid multiple scattering)
- Detector must run in target vacuum

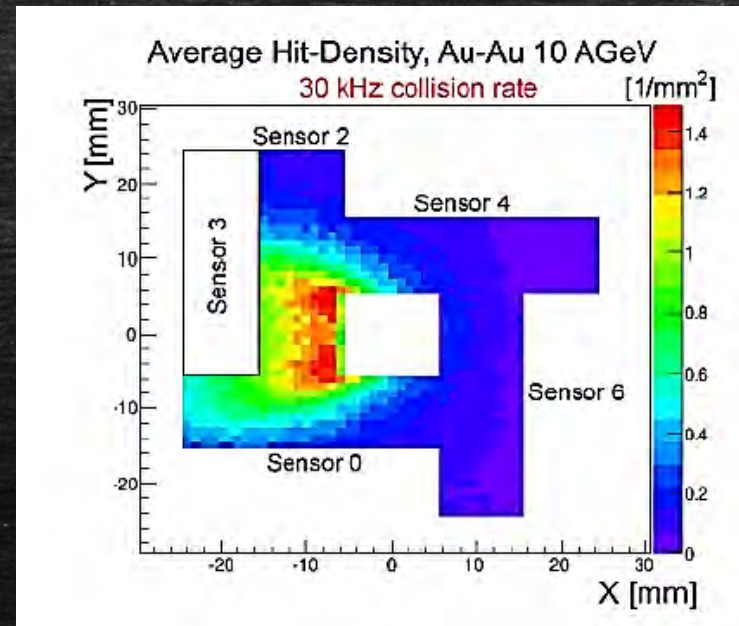
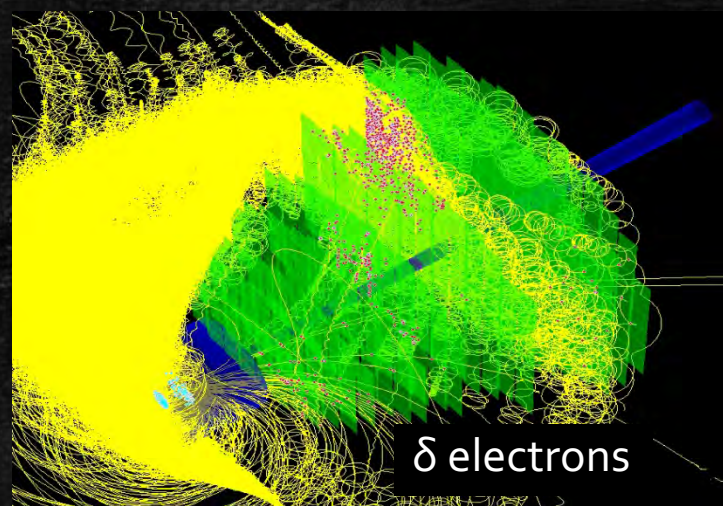
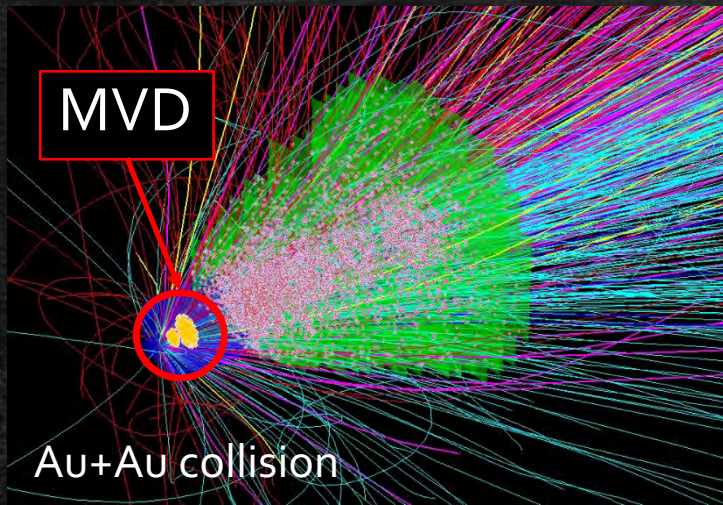


Very rare probes:

- High collision rate
 \Rightarrow Good radiation hardness
 \Rightarrow High rate capability

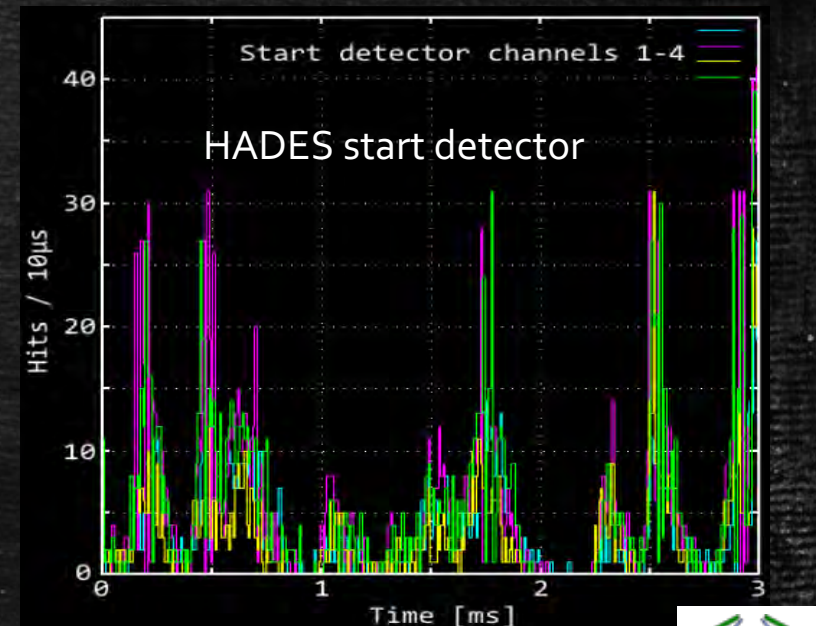
Need unique combination of high resolution and high rate.

Requirements: Rates and Radiation



Rates at first station (10% peak rate)

Hit rate: 7.5×10^7 hits/cm² (peak)
 Radiation damage (per run):
 $\sim 3 \times 10^{13}$ n_{eq} /cm²
 ~ 3 Mrad

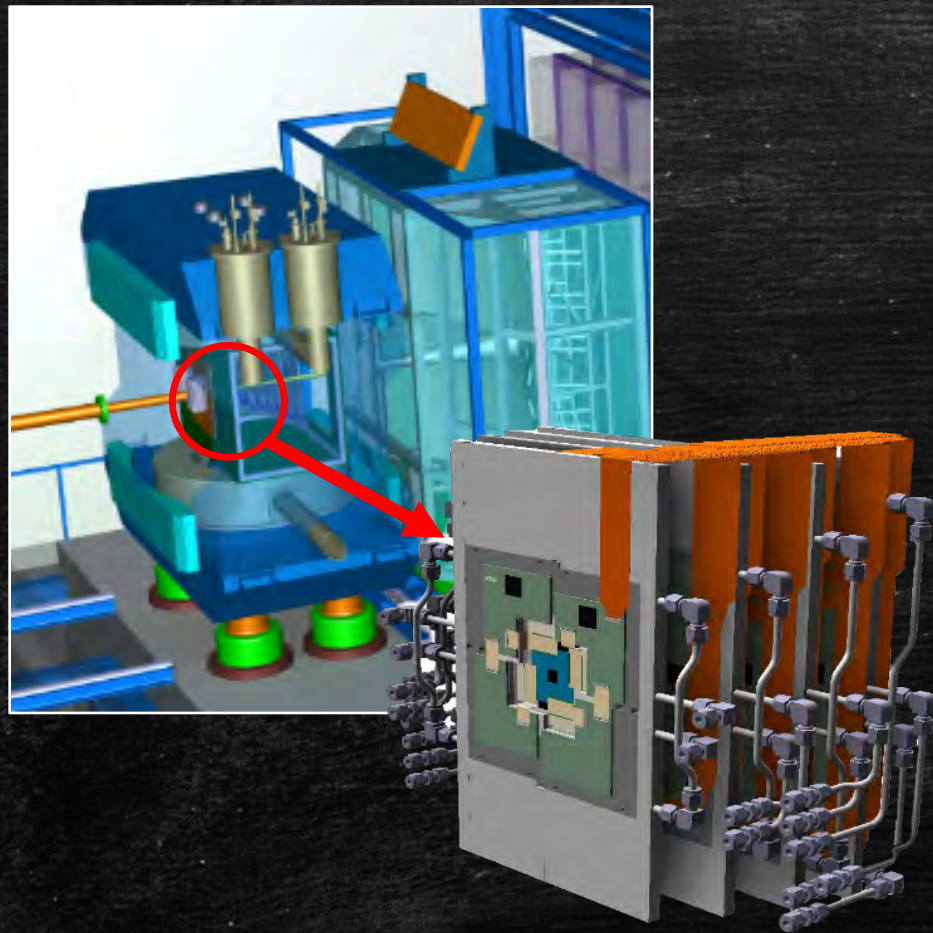


Beam fluctuations @SIS18



~ 10 times higher than ALICE ITS
 \rightarrow need for dedicated sensor

MVD - Fundamental Design Idea



Aim for high **collision rate capability**

⇒ 10^5 Au+Au collisions per second

⇒ 10^7 p-A collisions per second

Aim to **contribute to tracking**

⇒ 4 planar detector stations

Aim for **good sec. vertex resolution**

⇒ Operate in target vacuum

⇒ First station 5 cm from target

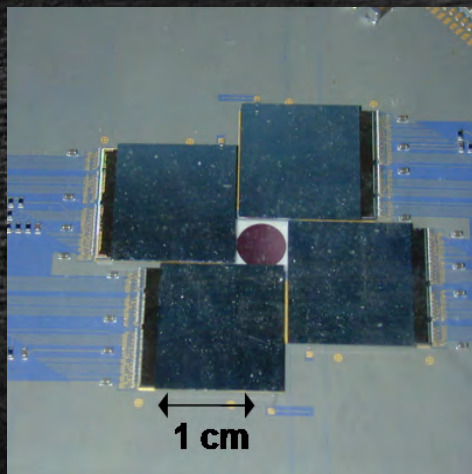
⇒ Silicon pixel ($\sim 5 \mu\text{m}$ resolution)

⇒ Thin stations

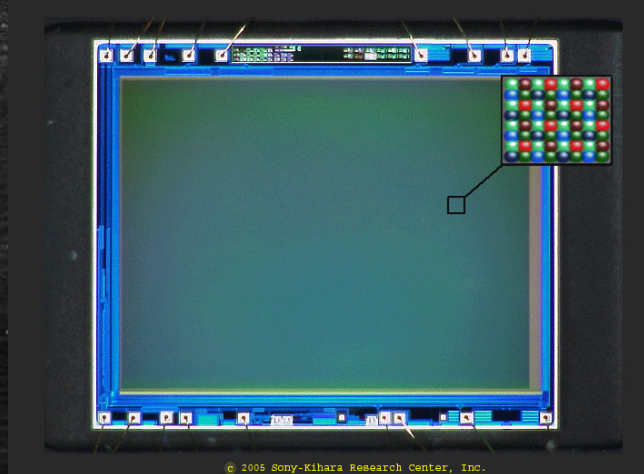
- $\sim 0.3 \% X_0$ (first station)

- $\sim 0.5 \% X_0$ (other stations)

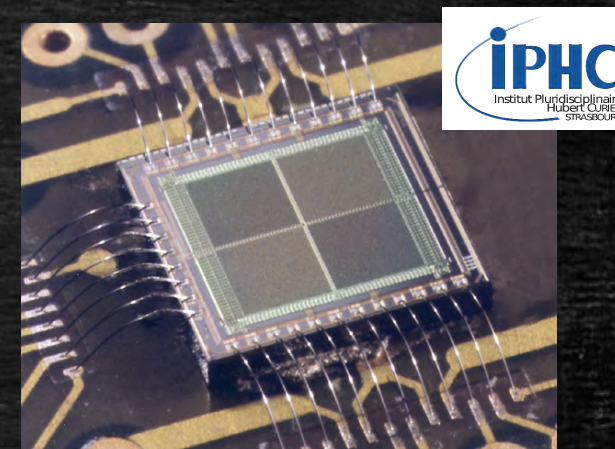
Sensor Technology Choice



Hybrid pixels



CCD

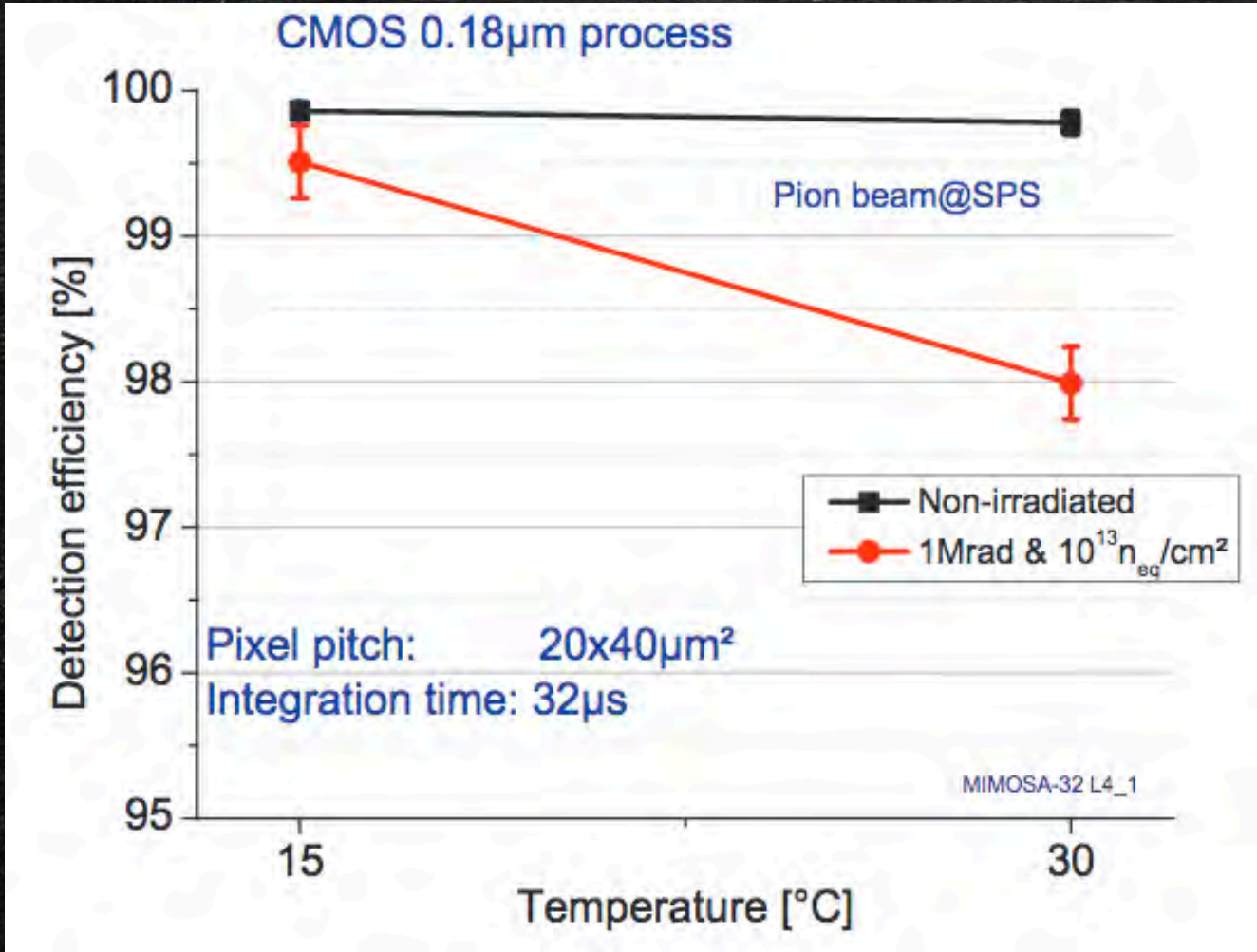


CMOS (MAPS)

Topic	CBM wish list	Hybrid Pixels	CCD	CMOS PS (MAPS) 2003
Single point resolution	~ 5 μm	~ 30 μm	~ 5 μm	1.5 μm
Material budget	Few 0.1 % X_0	~ 1 % X_0	~ 0.1 % X_0	~ 0.1 % X_0
Time resolution	~ 10 μs	~ 25 ns	~ 100 μs^*	~ 1 ms
Radiation hardness	~ 10^{15} $n_{\text{eq}}/\text{cm}^2$	> 10^{14} n_{eq}	~ 10^{10} n_{eq}^*	~ 10^{12} n_{eq}

CMOS Pixel Sensors (MAPS): the most promising sensor technology in 2003

Sensor R&D Progress With CMOS PS (MAPS)



Progress made possible by

- Hi-Resistivity EPI Layer
- Newer 180 nm TowerJazz CMOS chip production process
- Cooling mandatory for rad.hard.

CMOS (MAPS) used in science so far:



EUDET



STAR



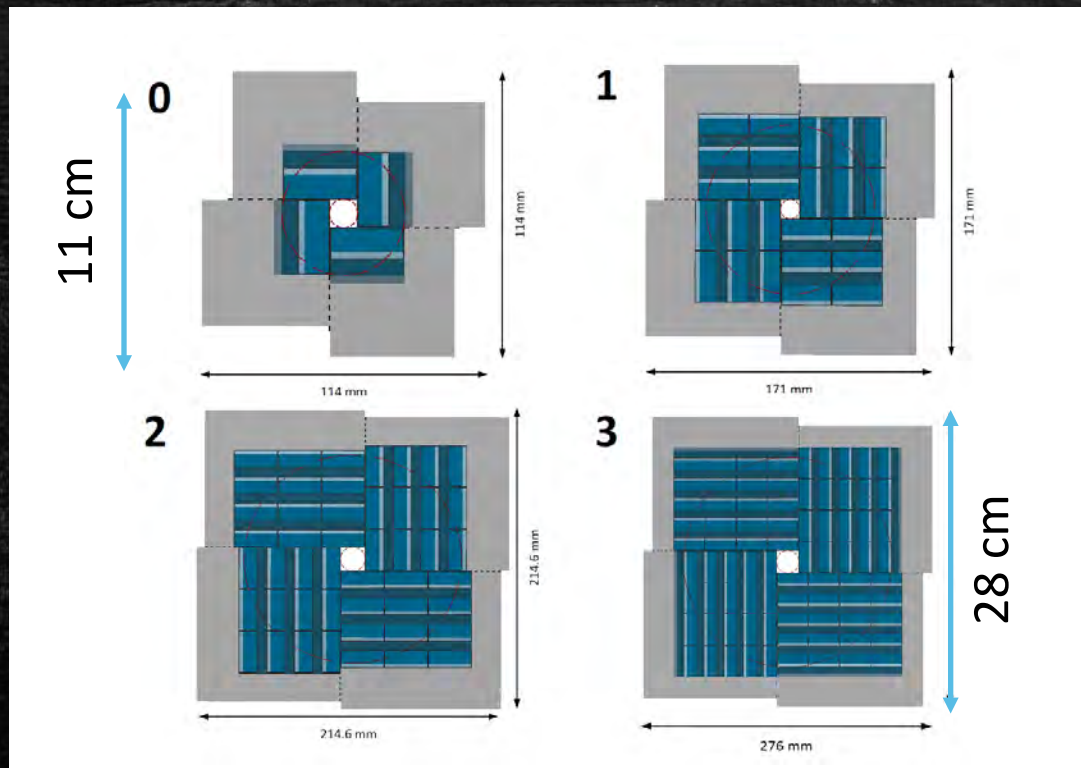
ALICE



NA61/SHINE

The requirements of CBM can be reached using CMOS PS (MAPS) sensors.

Detector Stations

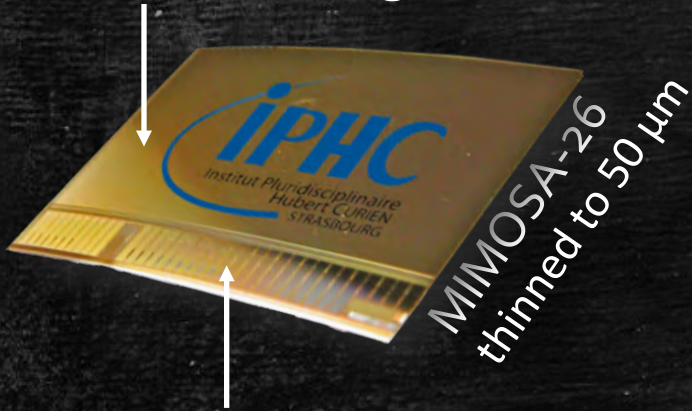


- Total number of four stations
- No. of sensors per station:
8 / 40 / 84 / 160
- Front- and back side equipped with sensors
- Carrier material (grey):
 - CVD diamond (first two stations)
 - TPG (next two stations)

Detector Composition and Integration

Sensing matrix

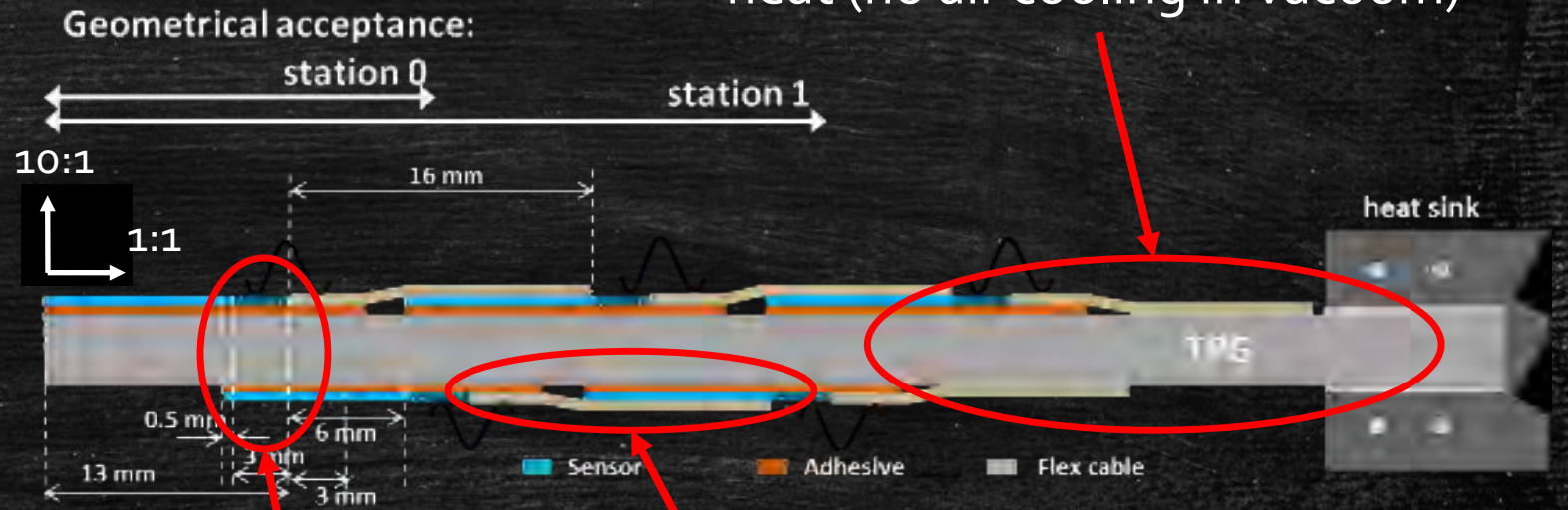
- 18.4 x 18.4 μm^2 pixel pitch
- 1152 x 576 pixel
- 119.2 μs integration time



Read-out area w/ integrated DAQ

- Threshold Voltages
- Signal discrimination
- Digital data pre-processing
- Slow control

Detector Composition/ Cross Section:



Holding structure to evacuate heat (no air cooling in vacuum)

Passive part of sensors covered by opposite sensor

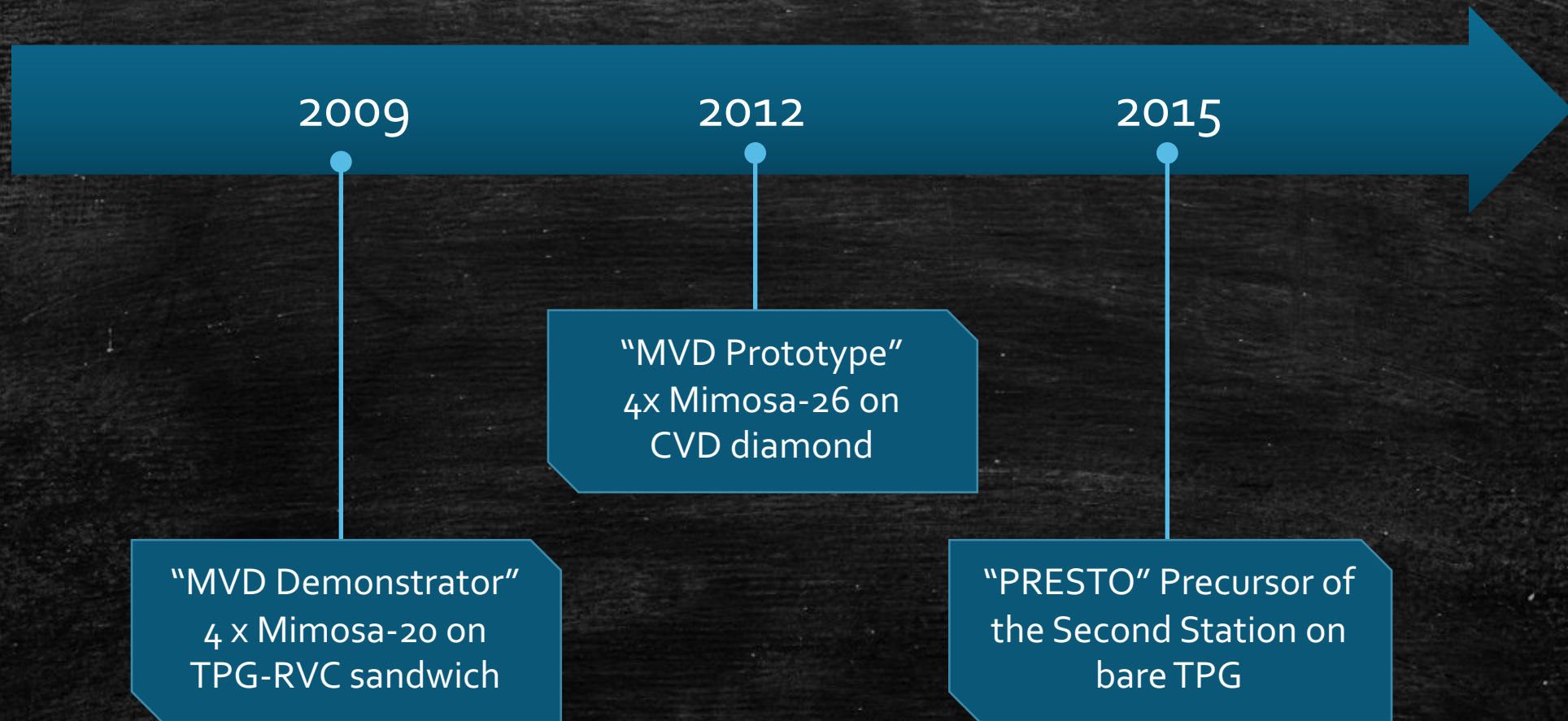
Very thin cables power and steer sensors

heat sink

TPG

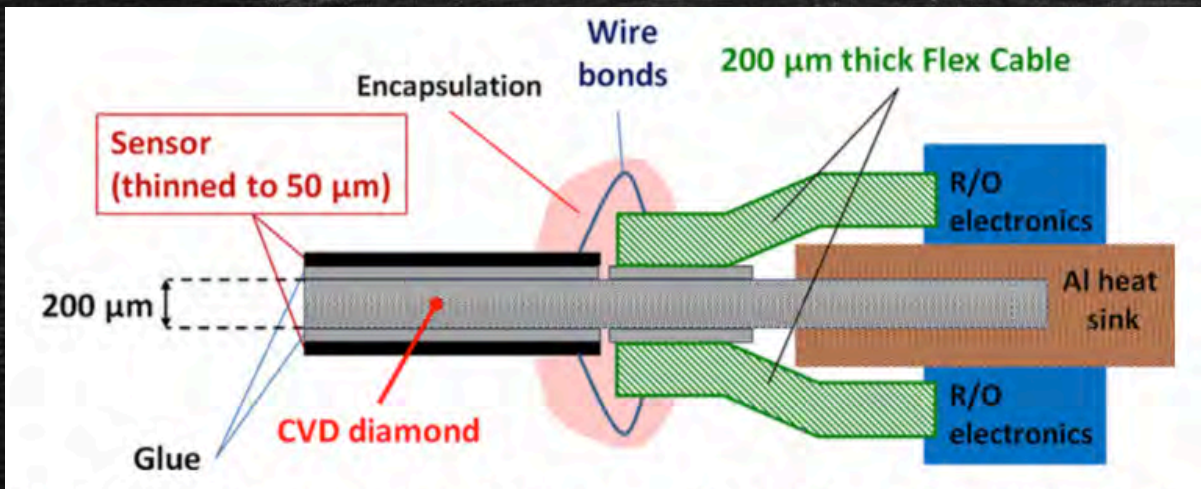
Sensor Adhesive Flex cable

Prototyping Timeline



Design Validation: Prototype 2012

Prototype cross section



Tested at CERN –SPS with π^- beam

Validated concepts:

- Double-sided integration
- Low material budget w/ thinned sensors
- Bonding technology to connect the sensors
- CVD diamond as carrier material



Important design choices validated ✓

Design Validation: PRESTO 2015

„PRESTO“ – PREcursor of the Second sTatiOn

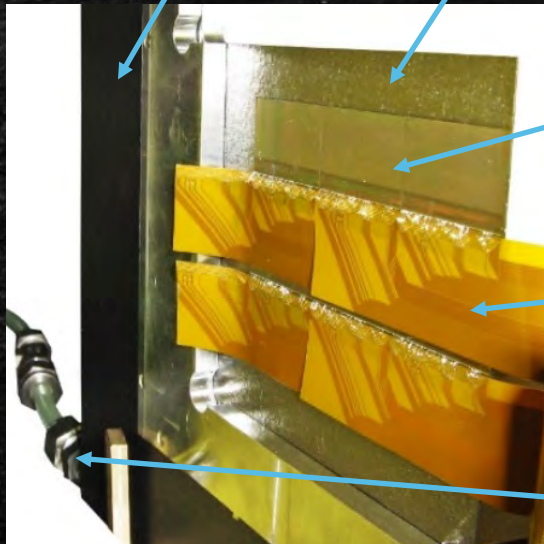
Liquid cooled Al-heat sink (easy unless you have to do it)

TPG holding structure,
high heat conductivity, low Z
(test thermal management)

50 μ m thin MIMOSA-26 sensor prototypes
(test placing, bonding, gluing)

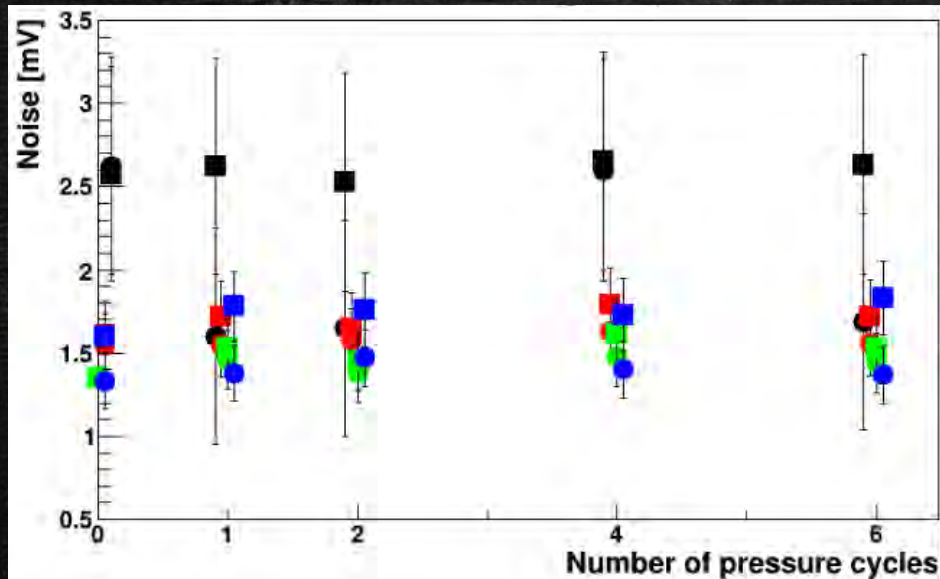
Micro cables
(test data transmission, noise etc)

Vacuum compatible coolant pipes



PRESTO – Results Vacuum

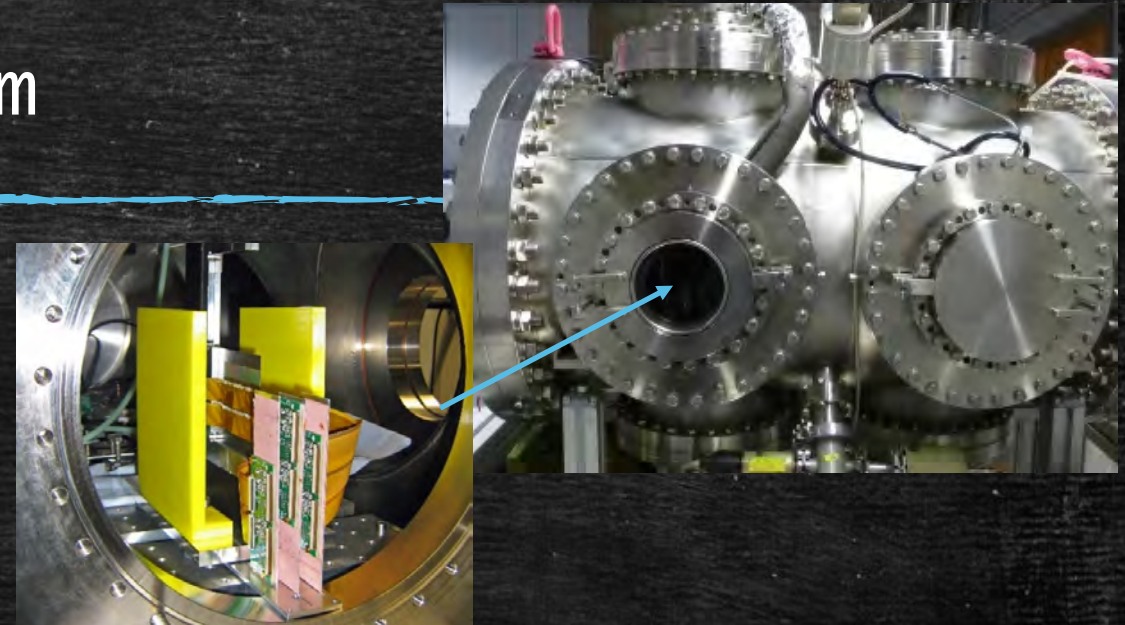
„PRESTO“ – PREcursor of the Second sTatiOn



Sensor Section (Bank):

- A
- B
- C
- D

- Temporal noise
- Fixed-pattern noise



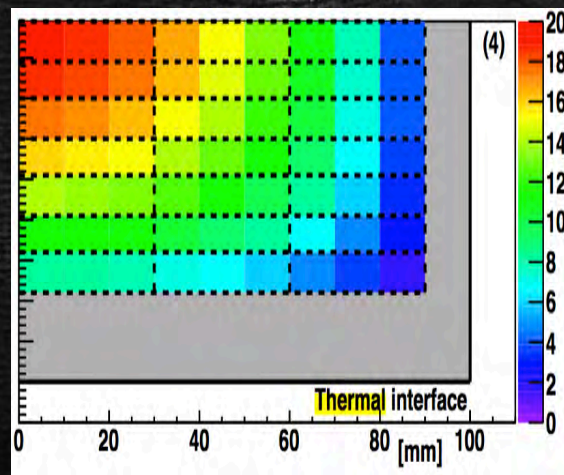
- Successful operation of the sensors in vacuum
- Gluing method with radiation hard glue demonstrated to be vacuum compatible

- Vacuum Suitability and Compatibility ✓
No performance loss observed after several pressure cycles @ 10^{-4} mbar

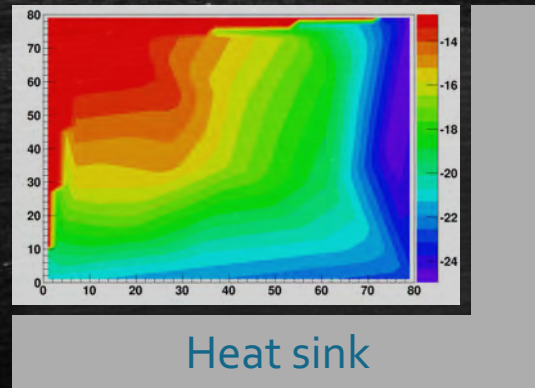
PRESTO – Results Cooling

„PRESTO“ – PREcursor of the Second sTatiOn

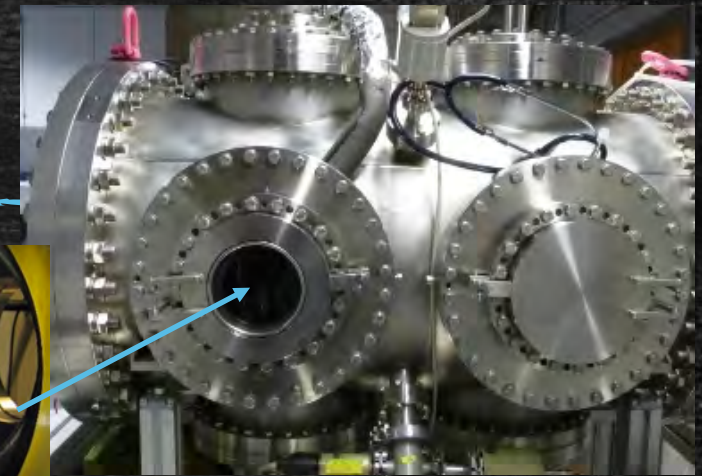
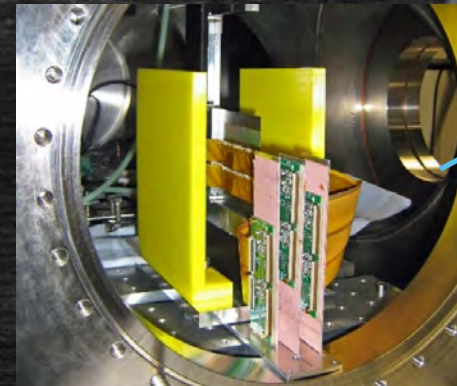
Simulation



Measurement (Pt100 sensors)



The gradients are in good agreement



Our cooling system Huber CC-405 can provide temperatures from - 50 °C to 30 °C

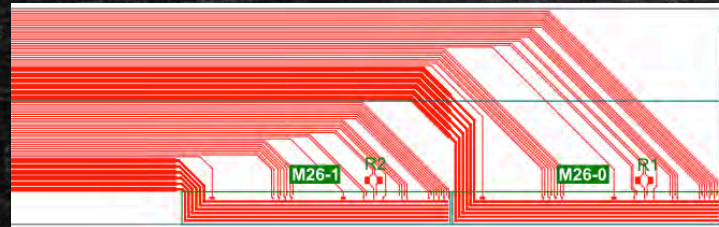
- Our prior thermal simulations were verified by our measurements .
- CVD diamond & TPG were validated as suitable carrier materials.

The performance is very promising. A thermal mockup system for the entire MVD is planned.

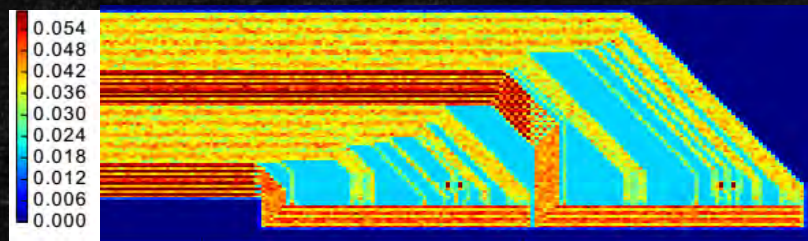
Material Budget Simulation: Cables



Crucial contribution to material: cables
=> need precise simulation model



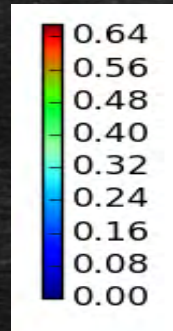
1) Design cable



2) Create Simulation

3) Combine with full detector CAD model

x/X_0 [%]



Blue $\leq 0.3 X_0$ (goal 1st station)
Green $\leq 0.5 X_0$ (goal other stations)

160 sensors

84 sensors

40 sensors

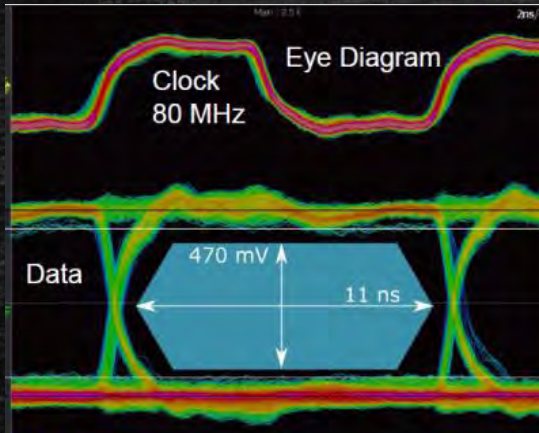
8 sensors

Detailed material simulation

Requirements met with copper technology (locally +20% => OK)

Data Acquisition and Front-End Electronics

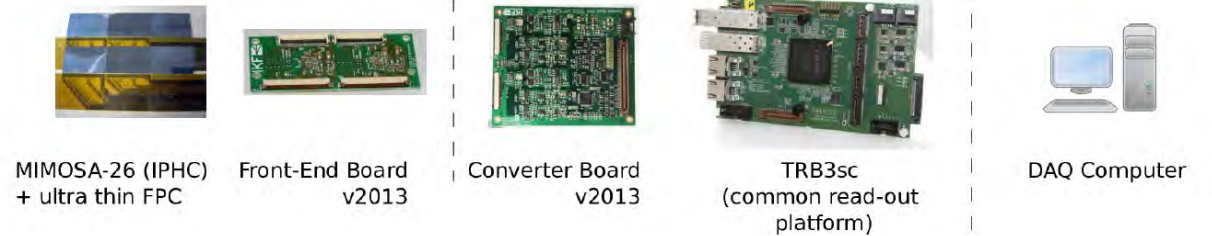
Reliable digital transmission



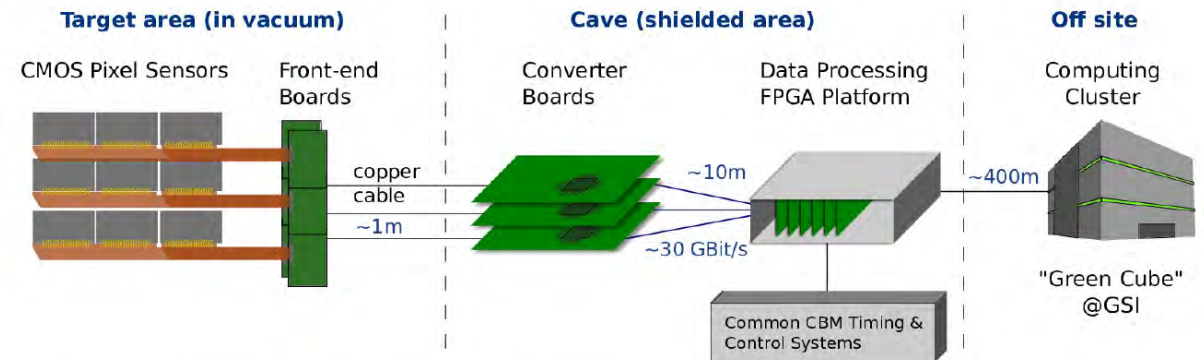
via the ultra-thin single-layer FPC cable



Precursor Implementation / Current Hardware



Schematic Representation of the Full MVD Read-out Chain



Read-out chain thoroughly tested and continuously updated

Summary & Conclusion

The CBM-MVD will help reconstructing rare probes

Requirements:

- Outstanding vertex resolution
 - ⇒ Low material budget
 - ⇒ excellent spatial resolution
 - ⇒ Vacuum operation
- Extreme rate capability
 - ⇒ Outstanding count rates
 - ⇒ High radiation tolerance

Concept:

- Dedicated CMOS - MAPS
- Cooling by heat conduction
- Ultra light cables

Status:

- Sensor R&D with IPHC on good track ✓
- Integration concept validated with our prototypes:
 - Material budget ✓
 - Vacuum operation and cooling ✓
 - Sensor integration ✓
 - Sensor readout ✓

Feasibility demonstrated with three generations of prototypes.

The CBM-MVD Collaboration

- AG Prof. Dr. Joachim Stroth
(Goethe University FFM)

Group of Prof. Marc Winter
(IPHC Strasbourg)



Tobias Bus, Michael Wiebusch, Erik Krebs, **Joachim Stroth**, Christian Müntz
Gisa Kretschmar, Philipp Klaus, Dennis Doering, Benjamin Linnik, Samir Amar-Youcef
Qiyang Li, Michal Koziel, Michael Deveaux, Tobias Tischler, Philipp Sitzmann

Not present: Jan Michel

Thank you for your attention!